

BOARD CHARACTERISTICS

Copper Layer Count: 4 Board Thickness: 1.5470 mm

Board overall dimensions: 101.0000 mm x 81.0000 mm

Min track/spacing: 0.1500 mm / 0.1500 mm Min hole diameter: 0.3000 mm

Copper Finish: HAL lead-free Impedance Control: Yes
Castellated pads: No Plated Board Edge: No

Edge card connectors: No

Layer Name	Туре	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	White	1	0
F.Paste	Top Solder Paste		0 mm		1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Green	3.3	0
F.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1785 mm	Not specified	4.56	0.02
In1.Cu	copper		0.035 mm		1	0
Dielectric	core	FR4	1.03 mm	Not specified	4.6	0.02
In2.Cu	copper		0.035 mm		1	0
Dielectric	prepreg	FR4	0.1785 mm	Not specified	4.56	0.02
B.Cu	copper		0.035 mm		1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Green	3.3	0
B.Paste	Bottom Solder Paste		0 mm		1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	White	1	0

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File: StepUp.ki	cad_pcb	
Title: Stepl	Jp	
Size: A4	Date: 2024-05-06	Rev: v0.1
KiCad E.D.A. 8	0.2	ld: 1/1
4	5	l'

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Copper Finish: Impedance Control: Yes Plated Board Edge: No οИ Castellated pads:

> οИ Edge card connectors:

Loss Tangent	Epsilon R	Color	Thickness (mm)	Material	Туре	Layer Name
0	1	White	mm 0	Not specified	Top Silk Screen	F.Silkscreen
0	1		mm 0		Top Solder Paste	F.Paste
0	3.3	Green	0.01 mm	Not specified	Top Solder Mask	F.Mask
0	1		0.035 mm		copper	F.Cu
0.02	4.56	Not specified	0.1785 mm	FR4	prepreg	Dielectric
0	1		0.035 mm		copper	ln1.Cu
0.02	4.6	Not specified	1.03 mm	FR4	core	Dielectric
0	1		0.035 mm		copper	In2.Cu
0.02	4.56	Not specified	0.1785 mm	FR4	prepreg	Dielectric
0	1		0.035 mm		copper	B.Cu
0	3.3	Green	0.01 mm	Not specified	Bottom Solder Mask	B.Mask
0	1		mm 0		Bottom Solder Paste	B.Paste
0	1	White	mm 0	Not specified	Bottom Silk Screen	B.Silkscreen

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